

# HCZ120N40M2

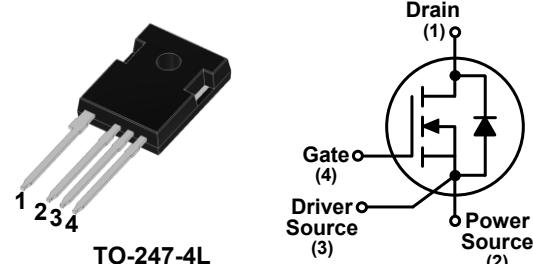
## N-Channel SiC Silicon Carbide Power MOSFET

1200 V, 57 A, 40 mΩ

### Features

- High switching speed with a low gate charge
- Fast intrinsic diode with low reverse recovery
- Robust Avalanche Capability
- 100% Avalanche Tested
- Pb-free, Halogen Free, and RoHS Compliant

$BV_{DSS}, T_c=25^\circ C$	$I_D, T_c=25^\circ C$	$R_{DS(on),typ}$	$Q_{g,typ}$
1200 V	57 A	40 mΩ	62 nC



### Benefits

- System efficiency improvement
- Higher frequency applicability
- Increased power density
- Reduced cooling effort

### Applications

- Solar inverter
- EV charging station
- UPS
- Industrial power supply



### Absolute Maximum Ratings ( $T_c = 25^\circ C$ unless otherwise noted)

Symbol	Parameter		Value	Unit
$V_{DSS}$	Drain to Source Voltage		1200	V
$V_{GS}$	Gate to Source Voltage (DC)		-10 / +22	V
$V_{GSop}$	Recommended Operation Value		-5...-3 / +18	V
$I_D$	Drain Current	Continuous ( $T_c = 25^\circ C$ )	57	A
		Continuous ( $T_c = 100^\circ C$ )	40	
$I_{DM}$	Drain Current	Pulsed (Note1)	142	A
$P_D$	Power Dissipation	( $T_c = 25^\circ C$ )	288	W
		Derate Above 25°C	1.9	W/°C
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to 175	°C
$T_L$	Maximum Lead Temperature for Soldering, 1/8" from Case for 10 Seconds		260	°C

### Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.52	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

### Package Marking and Ordering Information

Part Number	Top Marking	Package	Packing Method	Quantity
HCZ120N40M2	HCZ120N40M2	TO-247-4L	Tube	30 units

**Electrical Characteristics** ( $T_C = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain to Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}, I_{\text{D}} = 1 \text{ mA}$	1200			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 1200 \text{ V}, V_{\text{GS}} = 0 \text{ V}$		1	100	$\mu\text{A}$
		$V_{\text{DS}} = 1200 \text{ V}, V_{\text{GS}} = 0 \text{ V}, T_J = 175^\circ\text{C}$		10		
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}} = +22 \text{ V}, V_{\text{DS}} = 0 \text{ V}$			+100	$\text{nA}$
		$V_{\text{GS}} = -10 \text{ V}, V_{\text{DS}} = 0 \text{ V}$			-100	

**On Characteristics**

$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}} = V_{\text{DS}}, I_{\text{D}} = 10 \text{ mA}$ (tested after $V_{\text{GS}} = 22 \text{ V}, 1 \text{ ms pulse}$ )	2.0	3.0	4.5	V
$R_{\text{DS(on)}}$	Static Drain to Source On Resistance	$V_{\text{GS}} = 18 \text{ V}, I_{\text{D}} = 28 \text{ A}$		40.0	56.0	$\text{m}\Omega$
		$V_{\text{GS}} = 18 \text{ V}, I_{\text{D}} = 28 \text{ A}, T_J = 175^\circ\text{C}$		64.0		
		$V_{\text{GS}} = 15 \text{ V}, I_{\text{D}} = 28 \text{ A}$		55.5		
$g_{\text{fs}}$	Transconductance	$V_{\text{DS}} = 20 \text{ V}, I_{\text{D}} = 28 \text{ A}$		16.9		S

**Dynamic Characteristics**

$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}} = 800 \text{ V}, V_{\text{GS}} = 0 \text{ V}, f = 250 \text{ kHz}$		1668		$\text{pF}$
$C_{\text{oss}}$	Output Capacitance			105		
$C_{\text{rss}}$	Reverse Capacitance			4		
$E_{\text{oss}}$	Stored Energy in Output Capacitance	$V_{\text{DS}} = 0 \text{ V} \text{ to } 800 \text{ V}, V_{\text{GS}} = 0 \text{ V}$		42		$\mu\text{J}$
$C_{\text{o(er)}}$	Energy Related Output Capacitance			132		
$C_{\text{o(tr)}}$	Time Related Output Capacitance			201		
$Q_{\text{g(tot)}}$	Total Gate Charge	$V_{\text{DS}} = 800 \text{ V}, I_{\text{D}} = 28 \text{ A}, V_{\text{GS}} = -3 \text{ V} / 18 \text{ V}, \text{Inductive load}$		62		$\text{nC}$
$Q_{\text{gs}}$	Gate to Source Charge			20		
$Q_{\text{gd}}$	Gate to Drain "Miller" Charge			14		
$R_{\text{G}}$	Internal Gate Resistance	$f = 1 \text{ MHz}, V_{\text{AC}} = 30 \text{ mV}$		3.0		$\Omega$

**Switching Characteristics**

$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DS}} = 800 \text{ V}, I_{\text{D}} = 28 \text{ A}, V_{\text{GS}} = -3 \text{ V} / 18 \text{ V}, R_{\text{G}} = 6.8 \Omega, \text{FWD : HCH120S20D1, Inductive load}$		19		$\text{ns}$
$t_r$	Turn-On Rise Time			15		
$t_{\text{d(off)}}$	Turn-Off Delay Time			35		
$t_f$	Turn-Off Fall Time			8		
$E_{\text{on}}$	Turn-on Switching Energy			158		$\mu\text{J}$
$E_{\text{off}}$	Turn-off Switching Energy			100		
$E_{\text{tot}}$	Total Switching Energy			258		

**Electrical Characteristics** ( $T_C = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Source-Drain Diode Characteristics</b>						
$I_S$	Continuous Diode Forward Current	$V_{GS} = -3 \text{ V}$			57	A
$I_{SM}$	Pulsed Diode Forward Current	$V_{GS} = -3 \text{ V}$ (Note1)			142	
$V_{SD}$	Diode Forward Voltage	$V_{GS} = -3 \text{ V}, I_{SD} = 28 \text{ A}$		4.3		V
$t_{rr}$	Reverse Recovery Time	$V_{DD} = 800 \text{ V}, I_{SD} = 28 \text{ A},$ $dI_F/dt = 3000 \text{ A}/\mu\text{s}$ , Includes $Q_{oss}$		15		ns
$Q_{rr}$	Reverse Recovery Charge			219		nC
$I_{rrm}$	Peak Reverse Recovery Current			24		A

※Note 1 : Limited by maximum junction temperature.

## Typical Performance Characteristics

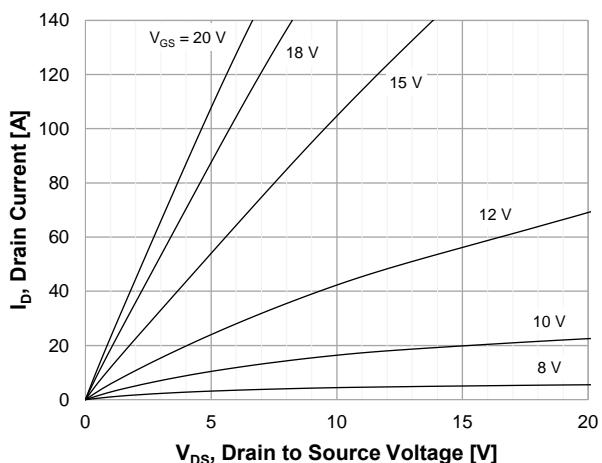
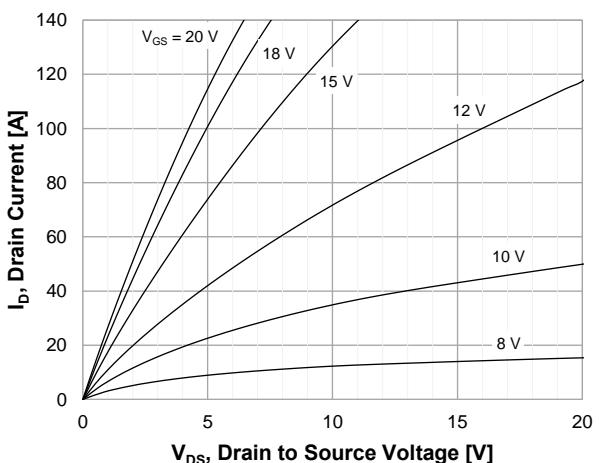
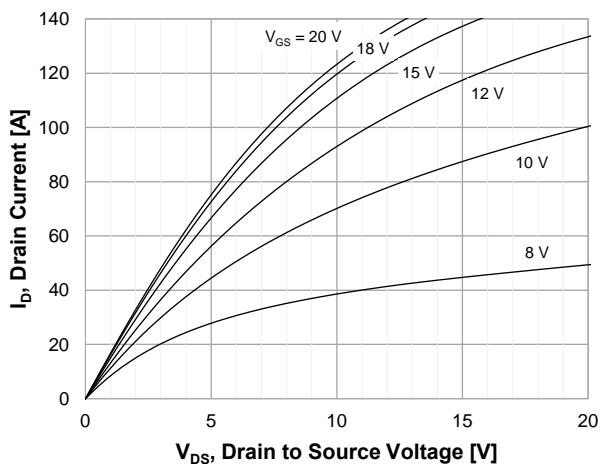
Figure 1. On-Region Characteristics  $T_J = -40^\circ\text{C}$ Figure 2. On-Region Characteristics  $T_J = 25^\circ\text{C}$ Figure 3. On-Region Characteristics  $T_J = 175^\circ\text{C}$ 

Figure 4. Normalized On-Resistance Characteristics vs. Temperature

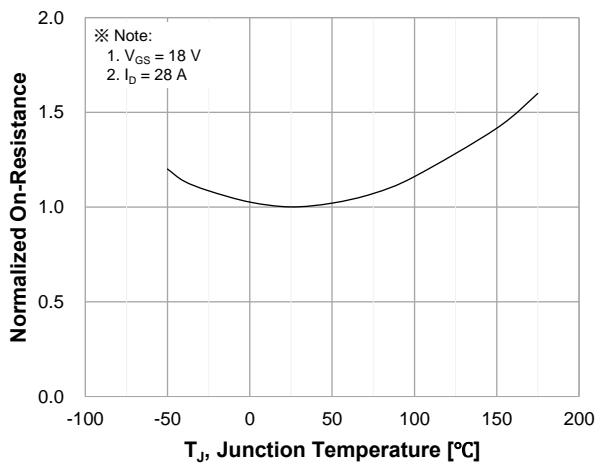
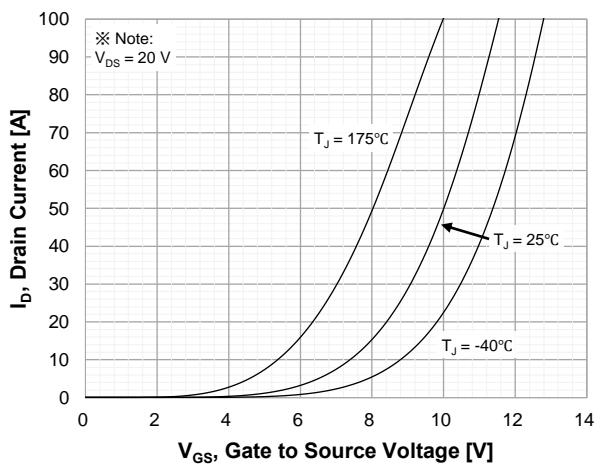
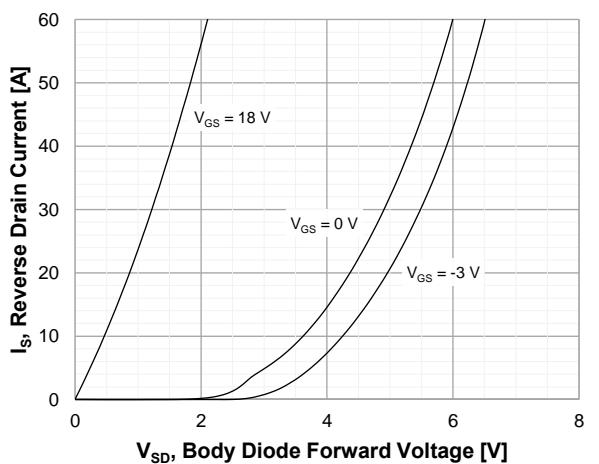
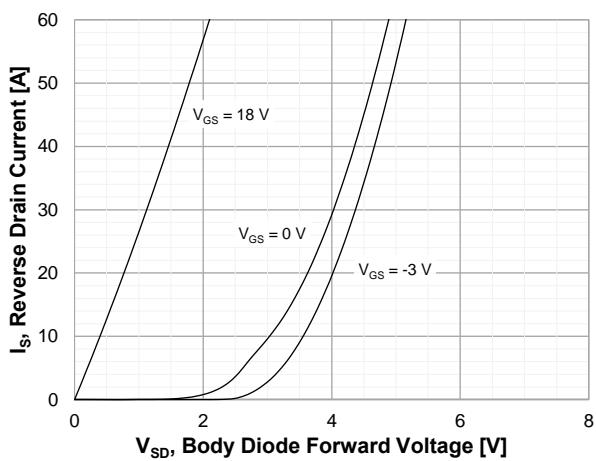


Figure 5. Transfer Characteristics

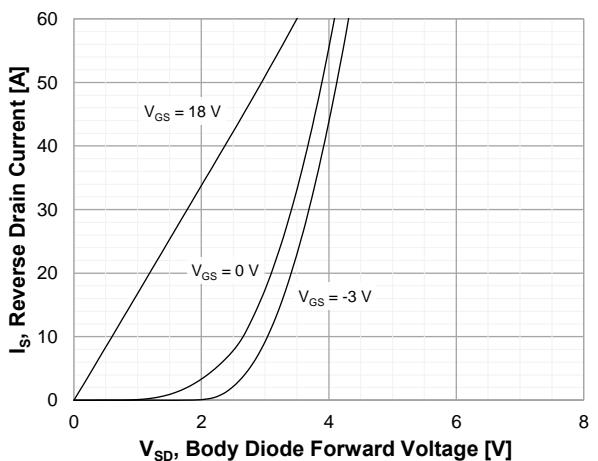
Figure 6. Diode Forward Voltage Characteristics vs. Source-Drain Current  $T_J = -40^\circ\text{C}$ 

## Typical Performance Characteristics

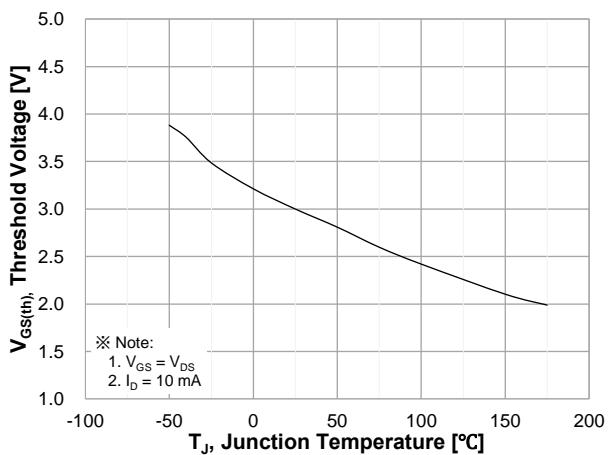
**Figure 7. Diode Forward Voltage Characteristics vs. Source-Drain Current  $T_J = 25^\circ\text{C}$**



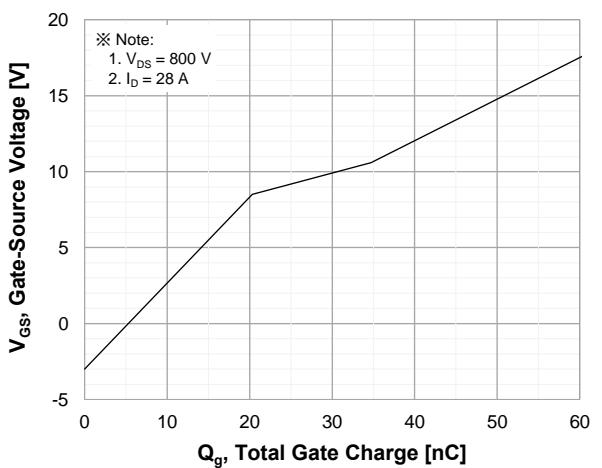
**Figure 8. Diode Forward Voltage Characteristics vs. Source-Drain Current  $T_J = 175^\circ\text{C}$**



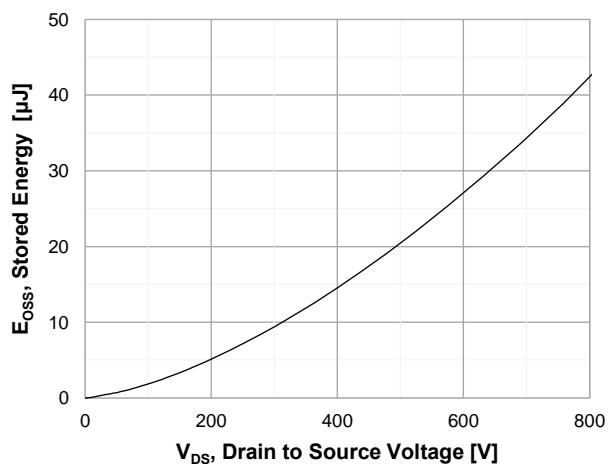
**Figure 9. Threshold Voltage vs. Temperature**



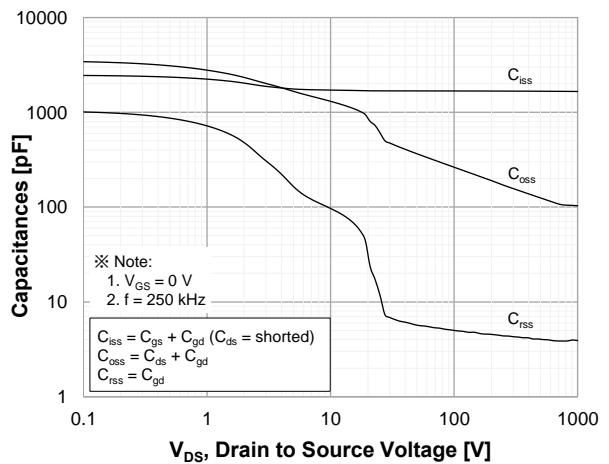
**Figure 10. Gate Charge Characteristics**



**Figure 11. Stored Energy in Output Capacitance**

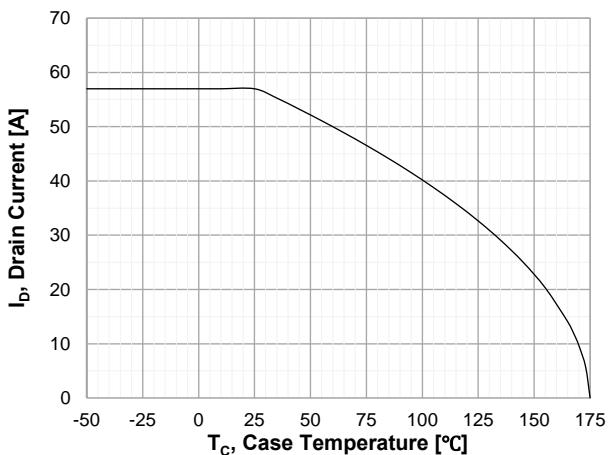


**Figure 12. Capacitance Characteristics**

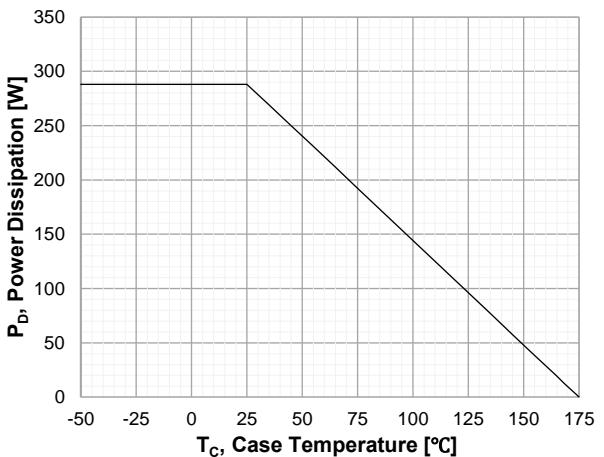


### Typical Performance Characteristics

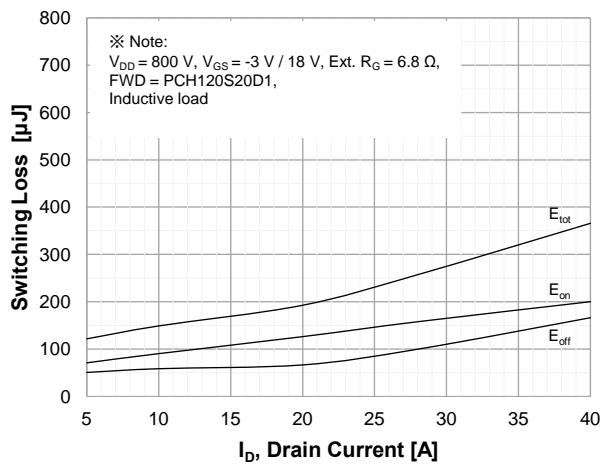
**Figure 13. Continuous Drain Current Derating vs. Case Temperature**



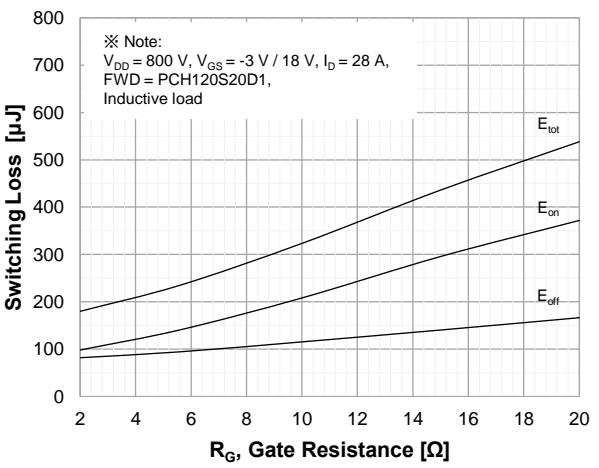
**Figure 14. Maximum Power Dissipation Derating vs. Case Temperature**



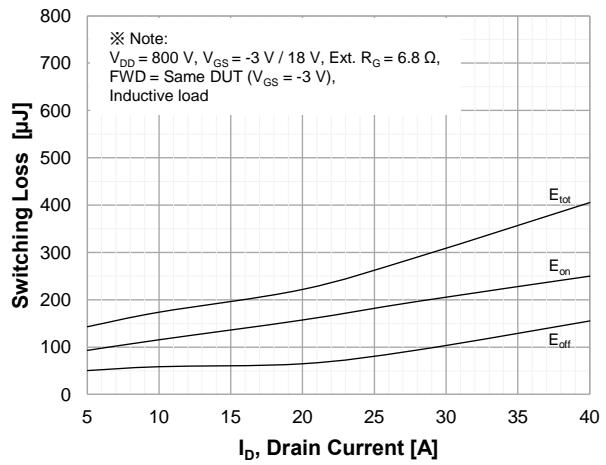
**Figure 15. Typ. Switching Losses vs. Drain Current**



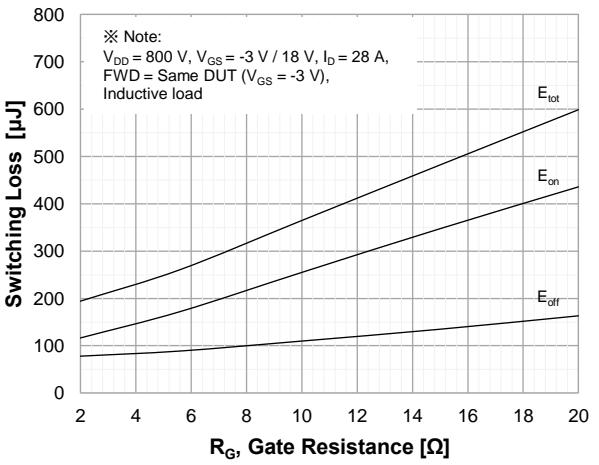
**Figure 16. Typ. Switching Losses vs. Gate Resistance**



**Figure 17. Typ. Switching Losses vs. Drain Current**



**Figure 18. Typ. Switching Losses vs. Gate Resistance**



## Typical Performance Characteristics

Figure 19. Maximum Safe Operating Area

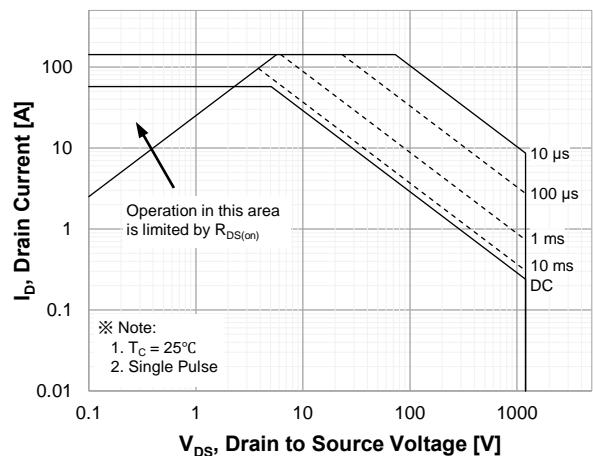


Figure 20. Transient Thermal Response Curve

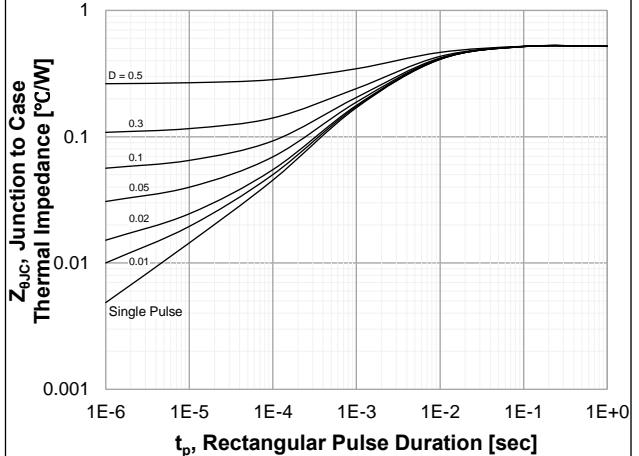


Figure 21. Inductive Load Switching Test Circuit and Waveforms

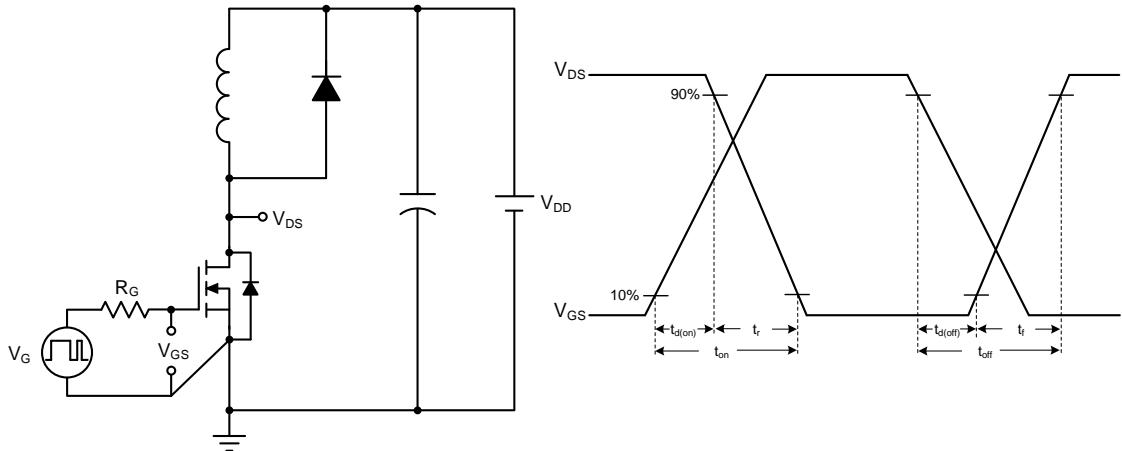
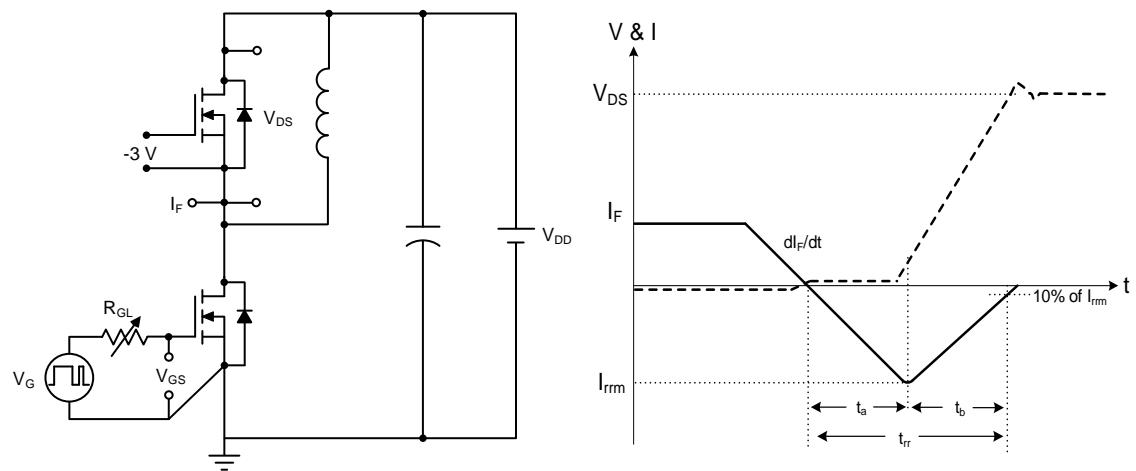
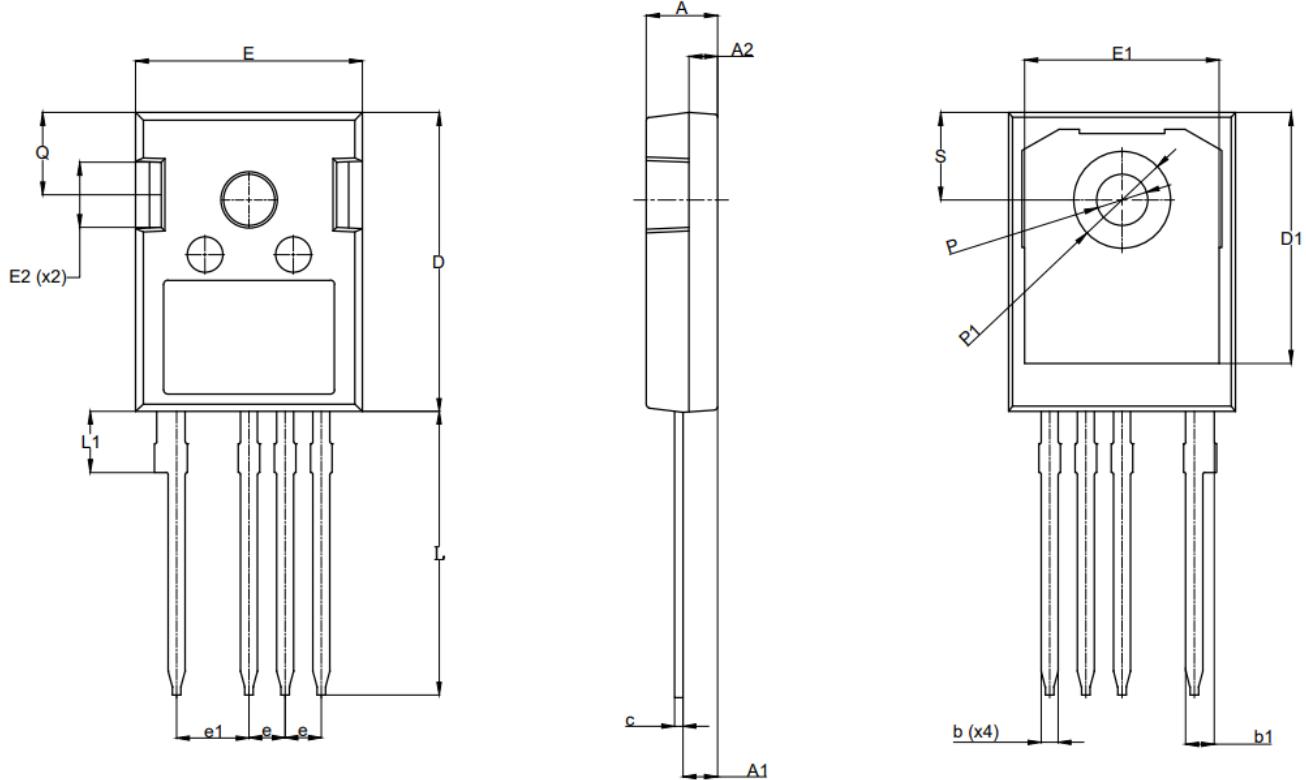


Figure 22. Peak Diode Recovery dv/dt Test Circuit and Waveforms



## Package Outlines

## TO-247-4L



SYMBOL	Common		
	DIMENSIONS MILLIMETER		
	MIN.	NOM.	MAX.
A	4.80	5.00	5.20
A1	2.29	2.42	2.54
A2	1.90	2.00	2.10
b	1.10	1.20	1.30
b1	1.86	2.01	2.15
c	0.50	0.60	0.70
D	20.90	21.00	21.10
D1	17.43	17.63	17.83
E	15.75	15.94	16.13
E1	13.46	13.66	13.86
E2	4.32	4.58	4.83
e	2.54 BSC.		
e1	5.08 BSC.		
L	19.80	19.95	20.10
L1	-	-	4.30
P	3.56	3.61	3.66
P1	6.75	6.80	6.85
Q	5.38	5.79	6.20
S	6.15 BSC.		

\* Dimensions in millimeters